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Introduction

Product Features

- High Burst Transfer Rate: 5MB/Sec Asynchronous, 10MB/Sec Synchronous SDT-10000 (14MB/sec Asynchronous, 40MB/sec Synchronous)
- Large 1 MB Buffer (SDT-9000 has 2MB; SDT-10000 has 10MB)
- 3.5" Standard Height, 5.25" Half Height Form Factors
- Embedded SCSI Interface (Ultra Wide for SDT-10000)
- Supports Variable or Fixed Record Length
- Supports SCSI-2 Sequential-Access Devices Command Set
- Read After Write (RAW)
- Frame Rewrite Function
- Three Levels of Error Correction Code (ECC)
- Quick Search (100 times normal Read/Write speed, 200 times with -9000)
- Random Read
- N-Group Write Option
- Dual Partition Option
- SCSI Disconnection/Arbitration

	SDT Tape Device (with data compression)				
	SDT-7000	SDT-7200	SDT-9000	SDT-10000	
Data Capacity	4 - 8** GB	4* GB	12 - 24** GB	20 - 40** GB	
Transfer Rate	0.78 - 1.55**	0.78*	1.2 - 2.4**	2.4 - 4.8**	
(sustained)	MB/sec.	MB/sec.	MB/sec.	MB/sec.	
Supported	DDS, DDS-2	DDS, DDS-2	DDS, DDS-2	DDS, DDS-2,	
Formats	DDS-DC, DCLZ		DDS-3, DDS-DC,	DDS-3, DDS-4,	
			DCLZ	DDS-DC, DCLZ	

*without compression ** assuming 2:1 compression ratio

Precautions

Installation

- Avoid placing the drive in a location subject to:
 - high humidity
 - high temperature
 - excessive dust
 - mechanical vibration
 - direct sunlight

Operation

- Do not move drive during operation, it may cause a malfunction.
- Avoid exposing drive to sudden changes from low to high temperature. Doing so may cause condensation to collect inside the drive. Should the ambient temperature suddenly rise while the drive is on, wait at least one hour before switching it off. Operating the drive immediately after a cause a malfunction.
- Do not switch the unit off with a tape in the drive.

Transportation

- Keep original packing material for future shipment of the drive.
- Remove any tape(s) before transport and repack drive as mentioned above.

Note:

This manual provides complete, step-by-step instructions for tape drive installation. Please read carefully and thoroughly before attempting installation and save it for future reference.



Installation

SCSI Connection/Setting the SCSI ID/Option Switches for SDT-7000/7200/9000



Note : = CLOSED Jumper installed = OPEN Jumper not installed

4 Precautions

SCSI Connection/Setting the SCSI ID for SDT-10000

Option Switches (DIP Switch) for SDT-10000

Terminator Power	Definition
OFF	Not provided
ON	Provided

DC Control-1	DC Control-2	Definition
OFF	OFF	Compression disabled at power-on. The host is allowed to control compression.
OFF	ON	Compression disabled at power-on. The host is not allowed to control compression.
ON	OFF	Compression enabled at power-on. The host is allowed to control compression.
ON	ON	Compression enabled at power-on. The host is not allowed to control compression.

Changing Form Factor

■ ④ If you want to change from HH 5.25" to 3.5":

1 Remove side rails

Remove four screws (a, b, c, d) securing the side rails (L, R) and then remove the side rails (L, R).

2 Remove 5.25" HH front panel

1. Push and unlock C and D at C' and D'.

2. Pull the lower part of front panel forward.

3 Install 3.5" front panel

- 1. Push and open lid.
- 2. Holding the lid open with your finger, push the front panel to ctach the chassis at A, B, C and D.

Note: Part E must locate on the pin.

■ ③ If you want to change a 5.25" HH front panel to a different colour 5.25" HH front panel:

1 Remove side rails

Remove four screws (a, b, c, d) securing the side rails (L, R) and then remove the side rails (L, R).

2 Remove 5.25" HH front panel

1. Push and unlock C and D at C' and D'.

2. Pull the lower part of front panel forward.

3 Install 5.25" front panel

- 1. Push and open lid.
- 2. Holding the lid open with your finger, push the front panel to ctach the chassis at A, B, C and D.

Note: Part E must locate on the pin.

4 Install side rails with screws

- 1. Put A into the hole A to catch the side rail (L)
- 2. Turn screw a first, and b next
- 3. Put B into the hole B to catch the side rail (R)
- 4. Turn screw c first, and d next

Note: Use the mounting screws removed in the A-1. Other screws may damage the drive mechanism

■ **O** If you want to change from 3.5" to 5.25" HH front panel:

1 Remove 3.5" front panel

- 1. Push and unlock C and D at C' and D'.
- 2. Pull the lower part of front panel forward.

Operation

Location of 3 LED's

2 Install 5.25" front panel

- 1. Push and open lid.
- 2. Holding the lid open with your finger, push the front panel to catch the chassis at A, B, C and D.

Note: Part E must locate on the pin.

3 Install side rails with screws

- 1. Put A into the hole A to catch the side rail (L).
- 2. Turn screw a first, and b next.
- 3. Put B into the hole B to catch the side rail (R).
- 4. Turn screw c first, and d next.

Note: Use the mouting screws removed in A-1. Other screws may damage the drive mechanism.

The drive's front panel has 3 LED's (BUSY, TAPE, and Status) and an eject button.

LED Indication for Drive Status

	LED		State		
BUSY	TAPE	STATUS	Activity	Cartridge	Other
			None	None	None
			SCSI	None	None
			Drive	Loading/Unloading	None
			Drive	Loading/Unloading	Write Protected
			None	Loaded	None
			SCSI	Loaded	None
			SCSI/Drive	Loaded	None
*		*	*	Loaded	Write Protected
			None	Loaded	Cleaning Tape at EOM
*		*	*	Loaded	Error Rate Warning
*	*		*	*	Cleaning Request
*	*		*	*	Selftest Failure
	*	*	*	*	Waiting for Reset
*		*	*	*	Waiting for Eject

off

on

0.25 sec on / 0.25 sec off

Drive Operation

Loading a Cassette

Insert a cassette into front panel slot with cassette's arrow pointing toward the drive. Drive's auto-load mechanism will draw cassette into unit.

Unloading a Cassette

Cassettes may be removed either in response to a SCSI command or by pressing the eject button. The latter causes a tape to go to BOM, the drive unthreads it, and ejects the cassette.

Write Protecting a Cassette

Sliding the tab on the back of a cassette write protects it. In this state, date may be read, but may not be written. (See below.)

Using a Cleaning Tape

The included head cleaner tape is designed to last the life of the drive. A cleaning tape should be used periodically to clean entire tape path. Drive will automatically request this cleaning operation. Drum rotation hours determine frequency of required head cleaning, normally each 24 hours.

Emergency Cassette Removal Procedure

If a tape becomes stuck inside the drive it may be removed manually.

- 1. Remove drive from its enclosure to gain access to the bottom left side of drive.
- 2. Remove drive's top cover to monitor degree of tape slack during the process.

Note:

Never touch anything inside the drive! It may cause a malfunction.

 Rotate Loading/Threading motor clockwise with a small Phillips (,,+") by placing it into the plastic screw head on the rear of drive (see figure). This will enable movement back to the threading mechanism's initial position.

Note:

To avoid drive damage, do not turn screw past its mechanical limit. To avoid tape damage, take up slack with ratchet on left side of drive.

- 4. Continue this procedure until tape is lifted from drive mechanism and ejected.
- 5. Return drive to an authorized service station for repair.

Interface Implementation

Supported SCSI Messages

- Abort Bus Device Reset Command Complete Disconnect Extended Message - Synchronous Data Transfer Request Identify (w/&w/o Disconnect)
- Initiator Detected Error Message Parity Error Message reject No Operation Restore Pointers Save Data Pointer

Supported SCSI Commands

Erase Inquiry Load/unload Locate Log Select Log Sense Mode Select (6) Mode Sense (6) Prevent Allow Medium Removal Read Read Block Limits Read Buffer Read Position Receive Diagnostic Results Release Unit Request Block Address Request Sense Reserve Unit Rewind Seek Block Send Diagnostic Space Test Unit Ready Verify Write Write Buffer Write Filemarks

Specifications

Dimensions

Temperature and Humidity Range

	Height Width Depth	3.5" Standard H 41.2mm (1.62 ii 101.6mm (4.0 ii 146.0mm (5.75	eight 1) 1) in)	5.25" Half Height 41.2mm (1.62 in) 146.0mm (5.75 in) 146.0mm (5.75 in)		Temperature Operating Non-Operati Non-Operati	ng (mech) ng (tape)	5° C tư -40° C -40° C	ο 40° C (ΔΤ C to 70° C (Δ C to 45° C (Δ	< 10° C/h) T< 20° C/h) T< 20° C/h)	
Acoustic No	ise					Humidity					
			(A) cur	ve weight		Operating		20 to 8	80% RH, noi	n-condensing	
	Streami	ng Write/Read	35db (4	A)				Maximum wet bulb temperature = 26° C			
	Insert/E	ject	60db (4	A)		Non-Operati Non-Operati	ing (mech) ing (tape)	ng (mech) 5 to 95% RH (Δ RH< 30%/h) ng (tape) 20 to 80% RH (Δ RH< 30%/h)		H< 30%/h) CH< 30%/h)	
Altitude					Power R	equirements			, , , , , , , , , , , , , , , , , , ,	,	
	Operatio	ng	0 to 70	00 feet					~		
						Voltage	Max rip	ple	Cur	rent	
Shock						5V ±/-5%	100mVr	n_n			
	Operatio	ng	No Dat	a Loss		12V + -10%	100mVr	у-р о-р	0.21 A	0.7 A	
			Half Si	ne			· · · ·	r			
			5 G Pa	nance	Suspended Particulate						
	3 axes, 3 directions *Interval 10 seconds			Operating		Less than 150 microgram/m ³					
			al 10 seconds						-		
					EMI						
	Non-Op	erating	No Dev	vice Damage		Radiated		FTZ/F	FCC class B,	VCCI-2 (Equival	ent)
			Half Si	ne		Conducted	d FTZ/FCC class B, VCCI-2 (Ec		VCCI-2 (Equival	ent)	
			90 G P	eak 3 ms		EGD		D' 1			
			(30 G I	a directions		ESD		Discha	arge	tion failura	
			J ares,	5 directions				< 20 k	$V \cdot No drive$	damage	
Vibration								< 20 h		dumage	
	Operati	าย	Swept	Sine 5 to 500 Hz	Air-cooli	ing Requirement					
	- r	-0	*0.25 0	G Peak 1 Octave/min.		Surrounding temperature		< 40° C			
			3 axes,	3 directions		\mathcal{C}					
						Clean air flow is recommended to minimise the possibility of data lo					ta loss.
	Non-Op	erating	Swept	Spine 5 to 500 Hz							
			*0.5 G	Peak 1 Octave/min.							
			3 axes,	3 directions							

SONY

DDS Tape Drive

SDT-7000 Series SDT-7200 Series SDT-9000 Series SDT-10000 Series

User's Guide Mode d'emploi Bedienungsanleitung Manual de instrucciones Manuale d'istruzione

DDS Tape Drive

SDT-7000 Series SDT-7200 Series SDT-9000 Series SDT-10000 Series

User's Guide Mode d'emploi Bedienungsanleitung Manual de instrucciones Manuale d'istruzione

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